imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







DT2042-04SO

Features

- Low Clamping Voltage
- Typical 9V at 10A 100ns, TLP
- Typical 9V at 10A 8µs/20µs
- IEC 61000-4-2 (ESD): Air ±30kV, Contact ±30kV
- IEC 61000-4-4 (EFT): 60A(5/50ns, I/O to V_{ss})
- IEC 61000-4-5 (Lightning): ±10A
- 4 Channels of ESD protection
- Low Channel Input Capacitance of 1.2pF Typical
- TLP Dynamic Resistance: 0.25Ω
- Typically Used for High Speed Ports such as USB 2.0, IEEE1394, VGA, Laptop and Personal Computers,
- Flat Panel Displays, Video Graphics Displays, SIM Ports
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

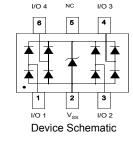


Top View

4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208⁽³⁾
- Weight: 0.016 grams (approximate)



Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT2042-04SO-7	Standard	BC5	7	8	3,000/Tape & Reel

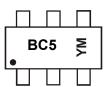
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

 See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



BC5 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	20	13	20	14	20	15	20	16	20	17	20	18
Code	A	4	E	3	()	[)	E		F	
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	Ν	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current, per IEC 61000-4-5	I _{PP}	±10	A	I/O to V _{SS} , 8/20 µs
Peak Pulse Power, per IEC 61000-4-5	P _{PP}	105	W	I/O to V _{SS} , 8/20 µs
Operating Voltage (DC)	V _{DC}	5.5	V	I/O to V _{SS}
ESD Protection – Contact Discharge, per IEC61000-4-2	V _{ESD_contact}	±30	kV	I/O to V _{SS}
ESD Protection – Air Discharge, per IEC 61000-4-2	V _{ESD_air}	±30	kV	I/O to V _{SS}
Operating Temperature	T _{OP}	-55 to +85	°C	
Storage Temperature	T _{STG}	-55 to +150	°C	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	PD	300	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	R _{θJA}	417	°C/W

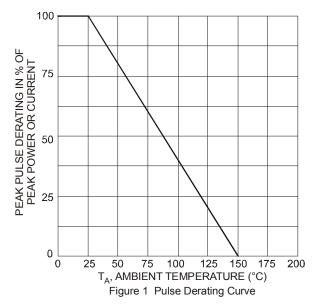
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

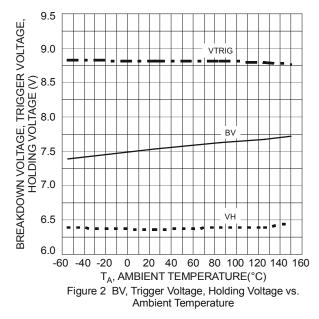
Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	V _{RWM}			5.5	V	I/O to V _{SS}
Reverse Current(Note6)	I _R			1	μA	V_R = 5V, any I/O to V_{SS}
Reverse Breakdown Voltage	V _{BR}	6		9	V	I_R = 1mA, I/O to V _{SS}
Forward Clamping Voltage	VF	-1.0	-0.8		V	I_F = -15mA, I/O to V _{SS}
Holding Voltage	V _H	5.5			V	
Trigger Voltage	VTRIG		9	9.5	V	
Reverse Clamping Voltage (Note 7)	V _{C_5A}		7.5		V	I _{PP} = 5A, I/O to V _{SS} , 8/20 μs
Reverse Clamping Voltage (Note 7)	V _{C_10A}		9	10.5	V	I _{PP} = 10A, I/O to V _{SS} , 8/20 μs
ESD Clamping Voltage	V _{ESD}		9		V	TLP, 10A, tp = 100 ns, I/O to V_{SS} , per Fig. 7
Dynamic Resistance	R _{DIF}		0.25		Ω	TLP, 10A, tp = 100 ns, I/O to V_{SS}
Channel Input Capacitance	C _{I/O}		1.2	1.5	pF	V _R = 2.5V, f = 1MHz
Variation of Channel Input Capacitance	$\Delta C_{I/O}$		0.02	_	pF	Vss = 0V,I/O = 2.5V, f =1MHz, T=25°C , I/O_x to V _{SS} – I/O_y to V _{SS}

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

6. Short duration pulse test used to minimize self-heating effect.

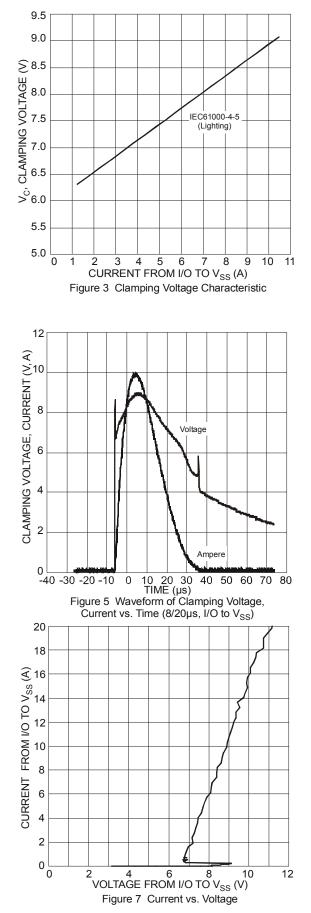
7. Clamping voltage value is based on an 8x20µs peak pulse current (Ipp) waveform.

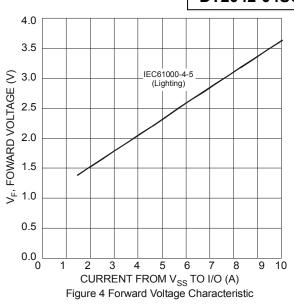


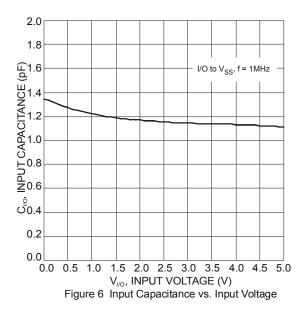




DT2042-04SO



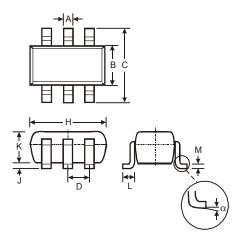






Package Outline Dimensions

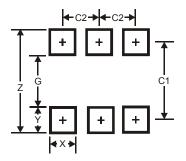
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT26							
Dim	Min	Max	Тур					
Α	0.35	0.50	0.38					
В	1.50	1.70	1.60					
С	2.70	3.00	2.80					
D			0.95					
н	2.90	3.10	3.00					
J	J 0.013		0.05					
К	1.00	1.30	1.10					
L	0.35	0.55	0.40					
М	0.10	0.20	0.15					
α	α 0° 8° —							
All D	All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
Z	3.20			
G	1.60			
Х	0.55			
Y	0.80			
C1	2.40			
C2	0.95			



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